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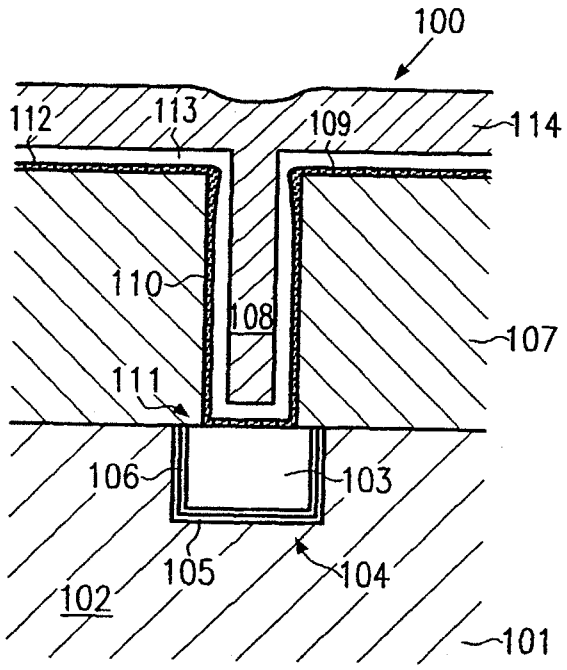
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(54) Title: METHOD OF FORMING A CATALYST CONTAINING LAYER OVER A PATTERNED DIELECTRIC



(57) Abstract: A metal layer is maybe formed by means of a plating process on a surface region of an underlying material catalytically activated in that a catalyst is deposited or incorporated by CVD, PVD or ALD at least partially during the deposition of the underlying material. In this way, superior metal seed layers may be formed in high aspect ratio vias of metallization structures.

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